the chip carrier and DIP. Table 1 gives the attributes of pin grid arrays compared to those of PLCCs, dual inline packages, and leadless chip carriers. Figure 6 shows a typical PGA.

Although electronic packages will continue to evolve, the traditional plastic or ceramic DIP can be expected to retain the largest share of the market for some years to come. The flatpak's future is limited, but chip carriers and PLCCs should see much greater use by the end of the decade. The pin grid array blends the mechanical advantages of the DIP with the ability to support high pin counts—it may be particularly attractive for the high I/O VLSI circuits of the future.

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